



低成本、单声道/立体声、 1.4W差分音频功率放大器

MAX9718/MAX9719

概述

MAX9718/MAX9719是差分输入音频功率放大器，适用于内置扬声器的便携式音频设备。差分输入结构改善了噪声抑制能力，并提供共模抑制。桥接负载(BTL)结构在提供高品质音频功率放大的同时，大大减少了外部元件数。MAX9718是单通道放大器，而MAX9719是用于立体声系统的双通道放大器。采用+5V单电源供电时，这两款器件的每个通道都能以小于1%的THD+N向4Ω负载输出1.4W的连续平均功率。这些器件既可以提供增益可调的放大器，也可以提供0dB、3dB和6dB的内部固定增益，以减少元件数目。

关断输入可以禁用偏置电压发生器和放大器，使静态电流损耗降低到100nA以内。MAX9718的关断输入可以设定为高电平有效或低电平有效。这些器件具有Maxim完备的杂音抑制电路，可以降低启动和关断过程的咔嗒/噼噓声。

MAX9718与LM4895引脚兼容，提供9焊球UCSP™，10引脚TDFN和10引脚μMAX®封装。MAX9719提供16引脚TQFN、16引脚TSSOP和16焊球UCSP封装。这些器件都工作在-40°C至+85°C扩展温度范围。

应用

移动电话

PDA

便携式装置

特性

- ◆ 2.7V至5.5V单电源供电
- ◆ 高PSRR，217Hz时为-93dB
- ◆ 以1%的THD+N为4Ω负载提供1.4W功率(每通道)
- ◆ 差分输入
- ◆ 内部固定增益，可以减少元件数目
- ◆ 可调增益选择(MAX9718A/H/MAX9719A)
- ◆ 100nA低功耗关断模式
- ◆ 上电/断电时无咔嗒/噼噓声
- ◆ 与LM4895引脚兼容的升级产品(MAX9718D/G)
- ◆ 兼容于1.8V逻辑电平

订购信息

PART	TEMP RANGE	PIN-PACKAGE	TOP MARK
MAX9718AEBL+TG45	-40°C to +85°C	3 x 3 UCSP	+ADX
MAX9718AETB+T	-40°C to +85°C	10 TDFN-EP*	+AAV

+表示无铅(Pb)/符合RoHS标准的封装。

*EP = 裸焊盘。

G45表示管芯带有保护层。

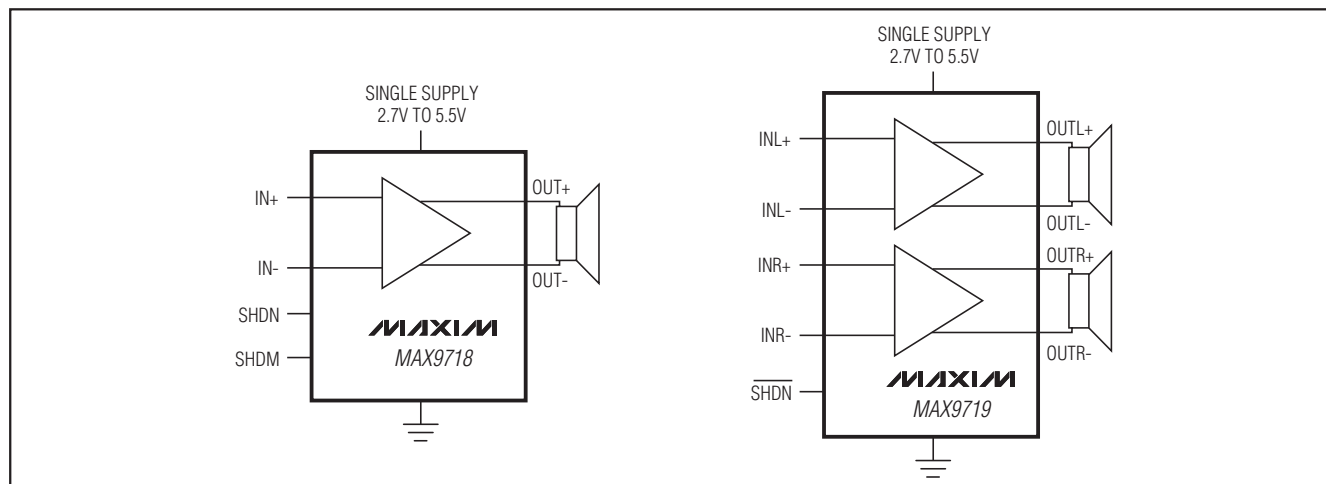
订购信息(续)在数据资料的最后给出。

引脚配置在数据资料的最后给出。

UCSP是 Maxim Integrated Products, Inc.的商标。

μMAX是 Maxim Integrated Products, Inc.的注册商标。

简化框图



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ABSOLUTE MAXIMUM RATINGS

Supply Voltage (V_{CC} to GND) -0.3V to +6V
 Any Other Pin to GND -0.3V to ($V_{CC} + 0.3$ V)
 IN_- , BIAS, SHDM, SHDN, $\overline{SHDN}$ Continuous Current 20mA
 OUT_- Short-Circuit Duration to GND or V_{CC} Continuous
 Continuous Power Dissipation ($T_A = +70^\circ\text{C}$)
 9-Bump UCSP (derate 5.2mW/ $^\circ\text{C}$ above $+70^\circ\text{C}$) 1067mW
 10-Pin TDFN (derate 24.4mW/ $^\circ\text{C}$ above $+70^\circ\text{C}$) 1951mW
 10-Pin μMAX (derate 10.3mW/ $^\circ\text{C}$ above $+70^\circ\text{C}$) 825mW
 16-Bump UCSP (derate 8.2mW/ $^\circ\text{C}$ above $+70^\circ\text{C}$) 1633mW
 16-Pin TQFN (derate 16.9mW/ $^\circ\text{C}$ above $+70^\circ\text{C}$) 1349mW
 16-Pin TSSOP (derate 21.3mW/ $^\circ\text{C}$ above $+70^\circ\text{C}$) 1702mW

Operating Temperature Range -40°C to $+85^\circ\text{C}$
 Junction Temperature $+150^\circ\text{C}$
 Storage Temperature Range -65°C to $+150^\circ\text{C}$
 Lead Temperature (soldering, 10s) $+300^\circ\text{C}$
 Soldering Temperature (reflow) $+260^\circ\text{C}$

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS—5V Supply

($V_{CC} = 5\text{V}$, $GND = 0$, $\overline{SHDN}/\overline{SHDN} = V_{CC}$ (MAX9718/MAX9719), SHDM = GND (MAX9718), $R_{IN} = R_F = 10\text{k}\Omega$ (MAX971_A/H), $T_A = +25^\circ\text{C}$. $C_{BIAS} = 0.1\mu\text{F}$, no load. Typical values are at $T_A = +25^\circ\text{C}$, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Supply Voltage	V _{CC}			2.7		5.5	V
Supply Current	I _{CC}	V _{IN-} = V _{IN+} = V _{BIAS} , T _A = -40°C to +85°C, per amplifier (Note 2)			5.0	7.5	mA
Shutdown Supply Current	I _{SHDN}	SHDN = SHDM = $\overline{\text{SHDN}}$ = GND, per amplifier			0.1	1	μA
$\overline{\text{SHDN}}$, SHDN, SHDM Threshold	V _{IH}	MAX9718A/B/C/D		0.7 × V _{CC}			V
	V _{IL}			0.3 × V _{CC}			
$\overline{\text{SHDN}}$, SHDN, SHDM Threshold	V _{IH}	MAX9718E/F/G/H		1.4			V
	V _{IL}			0.4			
Output Offset Voltage	V _{OS}	V _{IN-} = V _{IN+} = V _{BIAS}	A _V = 0dB, MAX971_A/H, MAX971_B/E		±1	±10	mV
			A _V = 3dB, MAX971_C/F		±1	±15	
			A _V = 6dB, MAX971_D/G		±1	±20	
Common-Mode Input Voltage	V _{IC}	Inferred from CMRR test	A _V = 0dB, MAX971_B/E	0.5		V _{CC} - 0.5	V
			A _V = 3dB, MAX971_C/F	0.5		V _{CC} - 0.6	
			A _V = 6dB, MAX971_D/G	0.5		V _{CC} - 0.8	
		External gain, MAX971_A/H		0.5		V _{CC} - 1.2	
Input Impedance	R _{IN}	MAX971_B/E, MAX971_C/F, MAX971_D/G		10	15	20	kΩ
Common-Mode Rejection Ratio	CMRR			-50	-60		dB
		f _N = 1kHz			-60		
Power-Supply Rejection Ratio	PSRR	V _{IN-} = V _{IN+} = V _{BIAS} , V _{RIPPLE} = 200mV _{P-P} , R _L = 8Ω, C _{BIAS} = 1μF	f = 217Hz		-93		dB
			f = 1kHz		-90		
Output Power	P _{OUT}	THD+N = 1%, f _{IN} = 1kHz (Note 4)	R _L = 8Ω	0.8	1.1		W
			R _L = 4Ω		1.4		
Total Harmonic Distortion Plus Noise	THD+N	R _L = 8Ω, f _{IN} = 1kHz, P _{OUT} = 0.75W, V _{CC} = 5V, A _V = 6dB (Note 5)			0.002		%

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ELECTRICAL CHARACTERISTICS—5V Supply (continued)

($V_{CC} = 5V$, $GND = 0$, $\overline{SHDN}/\overline{SHDN} = V_{CC}$ (MAX9718/MAX9719), $\overline{SHDM} = GND$ (MAX9718), $R_{IN} = R_F = 10k\Omega$ (MAX971_A/H), $T_A = +25^\circ C$. $C_{BIAS} = 0.1\mu F$, no load. Typical values are at $T_A = +25^\circ C$, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Gain Accuracy		MAX971_B/E, MAX971_C/F, MAX971_D/G			± 1	%
Channel-to-Channel Gain Matching		MAX9719B/E, MAX9719C/F, MAX9719D/G			± 1	%
Signal-to-Noise Ratio	SNR	$P_{OUT} = 1W$, $R_L = 8\Omega$		-104		dB
Thermal-Shutdown Threshold				+160		$^\circ C$
Thermal-Shutdown Hysteresis				15		$^\circ C$
Maximum Capacitive Drive	C_{LOAD}	Bridge-tied capacitance		500		pF
Power-Up/Enable from Shutdown Time	t_{PU}			10		ms
Shutdown Time	t_{SHDN}			3.5		μs
Turn-Off Transient	V_{POP}	(Note 6)		50		mV
Crosstalk		MAX9719, $f_{IN} = 1kHz$		-85		dB

ELECTRICAL CHARACTERISTICS—3V Supply

($V_{CC} = 3V$, $GND = 0$, $\overline{SHDN}/\overline{SHDN} = V_{CC}$ (MAX9718/MAX9719), $\overline{SHDM} = GND$ (MAX9718), $R_{IN} = R_F = 10k\Omega$ (MAX971_A/H), $T_A = +25^\circ C$. $C_{BIAS} = 0.1\mu F$, no load. Typical values are at $T_A = +25^\circ C$, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Supply Current	I _{CC}	V _{IN-} = V _{IN+} = V _{BIAS} , T _A = -40°C to +85°C, per amplifier (Note 2)			3.8	6.0	mA
Shutdown Supply Current	I _{SHDN}	SHDN = SHDM = $\overline{\text{SHDN}}$ = GND, per amplifier			0.1	1	μA
$\overline{\text{SHDN}}$, SHDN, SHDM Threshold	V _{IH}			0.7 x V _{CC}		V	
	V _{IL}			0.3 x V _{CC}			
Common-Mode Bias Voltage	V _{BIAS}	(Note 3)		V _{CC} /2 - 5%	V _{CC} /2	V _{CC} /2 + 5%	V
Output Offset Voltage	V _{OS}	V _{IN-} = V _{IN+} = V _{BIAS}	A _V = 0dB, MAX971_A/H MAX971_B/E	±1		±10	mV
			A _V = 3dB, MAX971_C/F	±1		±15	
			A _V = 6dB, MAX971_D/G	±1		±20	
Common-Mode Input Voltage	V _{IC}	Inferred from CMRR test	A _V = 0dB, MAX971_B/E	0.5		V _{CC} - 0.7	V
			A _V = 3dB, MAX971_C/F	0.5		V _{CC} - 0.8	
			A _V = 6dB, MAX971_D/G	0.5		V _{CC} - 1.0	
		External gain, MAX971_A/H		0.5		V _{CC} - 1.2	
Input Impedance	R _{IN}	MAX971_B/E, MAX971_C/F, MAX971_D/G		10	15	20	kΩ
Common-Mode Rejection Ratio	CMRR			-50	-60		dB
		f _N = 1kHz				-70	
Power-Supply Rejection Ratio	PSRR	V _{IN-} = V _{IN+} = V _{BIAS} , V _{RIPPLE} = 200mV _{P-P} , R _L = 8Ω, C _{BIAS} = 1μF	f = 217Hz			-93	dB
			f = 1kHz			-90	

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ELECTRICAL CHARACTERISTICS—3V Supply (continued)

($V_{CC} = 3V$, $GND = 0$, $\overline{SHDN}/\overline{SHDN} = V_{CC}$ (MAX9718/MAX9719), $\overline{SHDN} = GND$ (MAX9718), $R_{IN} = R_F = 10k\Omega$ (MAX971_A/H), $T_A = +25^\circ C$. $C_{BIAS} = 0.1\mu F$, no load. Typical values are at $T_A = +25^\circ C$, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output Power	P_{OUT}	$R_L = 8\Omega$, $THD+N = 1\%$, $f_{IN} = 1kHz$ (Note 4)		475		mW
Total Harmonic Distortion Plus Noise	$THD+N$	$R_L = 8\Omega$, $f_{IN} = 1kHz$, $P_{OUT} = 0.25W$, $A_V = 6dB$		0.003		%
Thermal-Shutdown Threshold				+160		$^\circ C$
Thermal-Shutdown Hysteresis				15		$^\circ C$
Maximum Capacitive Drive	C_{LOAD}	Bridge-tied capacitance		500		pF
Power-Up/Enable from Shutdown Time	t_{PU}			10		ms
Shutdown Time	t_{SHDN}			3		μs
Turn-Off Transient	V_{POP}	(Note 6)		40		mV
Crosstalk		MAX9719, $f_{IN} = 1kHz$		-85		dB

Note 1: All specifications are 100% tested at $T_A = +25^\circ C$. Specifications over temperature ($T_A = T_{MIN}$ to T_{MAX}) are guaranteed by design, not production tested.

Note 2: Quiescent power-supply current is specified and tested with no load. Quiescent power-supply current depends on the offset voltage when a practical load is connected to the amplifier. Guaranteed by design.

Note 3: Common-mode bias voltage is the voltage on $BIAS$ and is nominally $V_{CC}/2$.

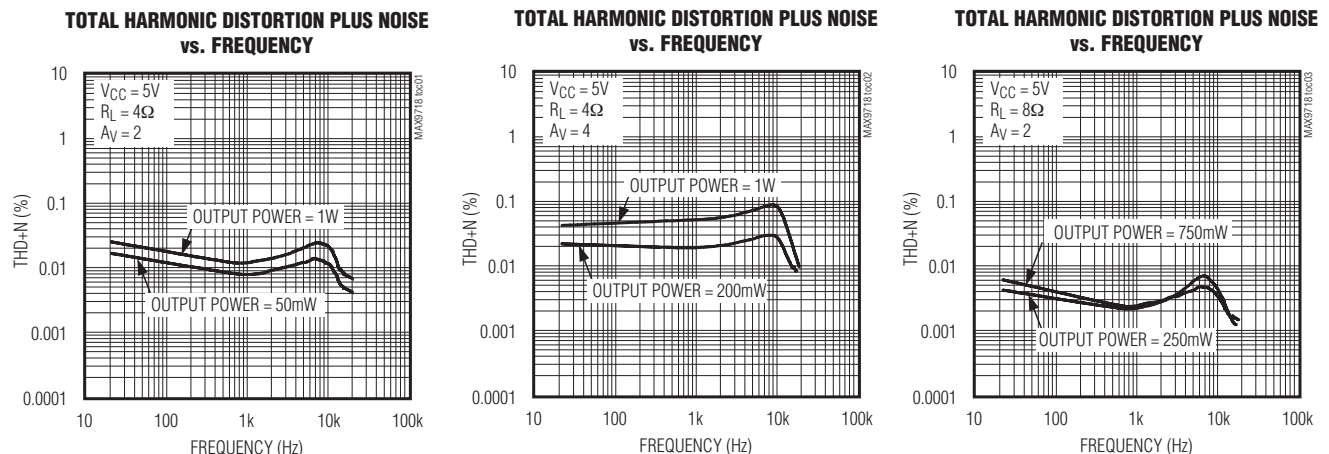
Note 4: Output power is specified by a combination of a functional output current test and characterization analysis.

Note 5: Measurement bandwidth for $THD+N$ is 22Hz to 22kHz.

Note 6: Peak voltage measured at power-on, power-off, into or out of $\overline{SHDN}$. Bandwidth defined by A-weighted filters, inputs at GND . V_{CC} rise and fall times greater than or equal to 1ms.

典型工作特性

($V_{CC} = 5V$, $C_{BIAS} = 0.1\mu F$, $THD+N$ measurement bandwidth = 22Hz to 22kHz, $T_A = +25^\circ C$, unless otherwise noted.)



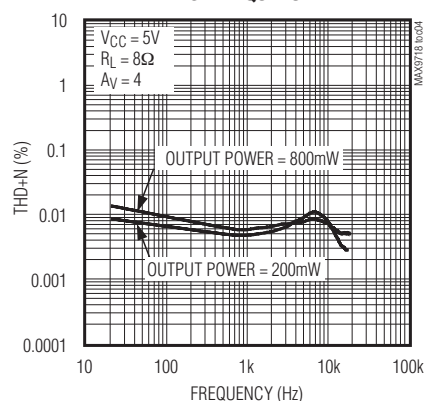
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典型工作特性(续)

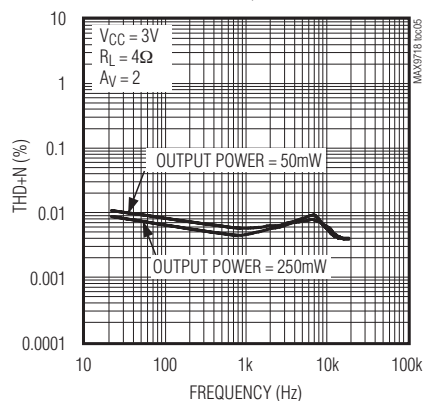
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MAX9718/MAX9719

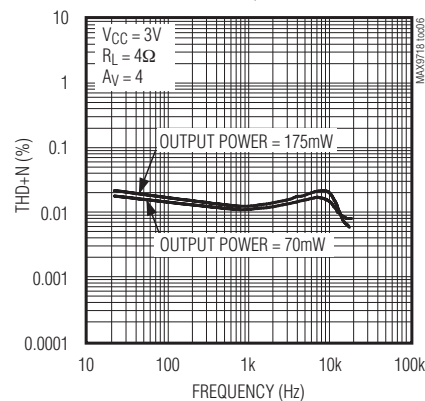
**TOTAL HARMONIC DISTORTION PLUS NOISE
vs. FREQUENCY**



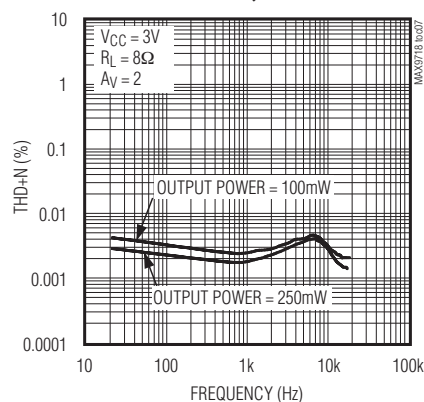
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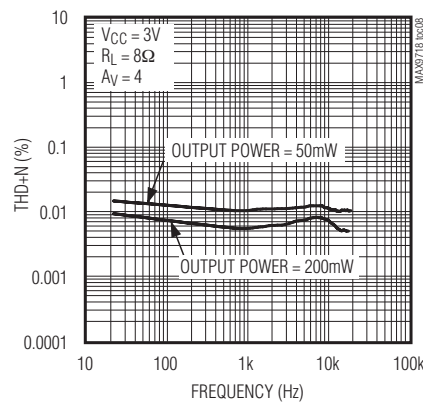
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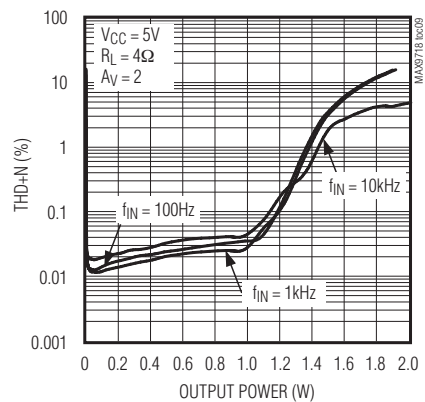
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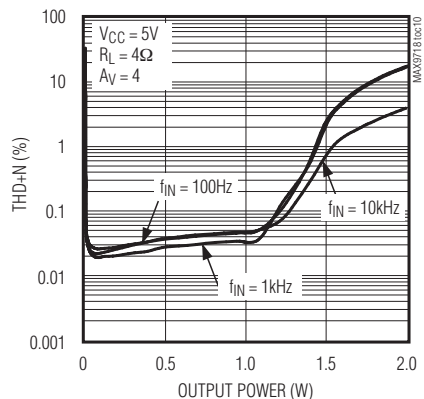
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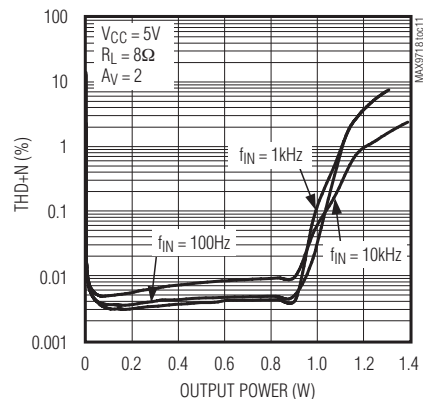
**TOTAL HARMONIC DISTORTION PLUS NOISE
vs. OUTPUT POWER**



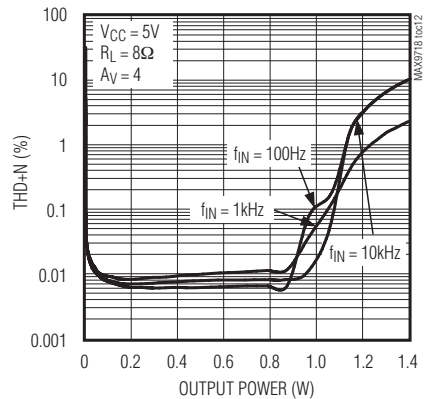
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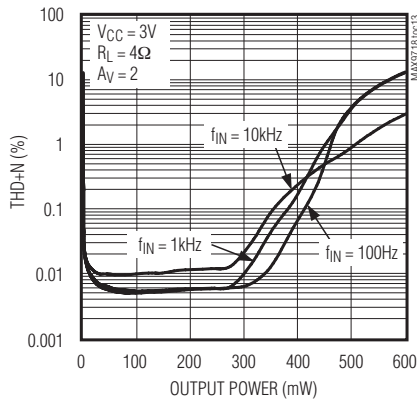
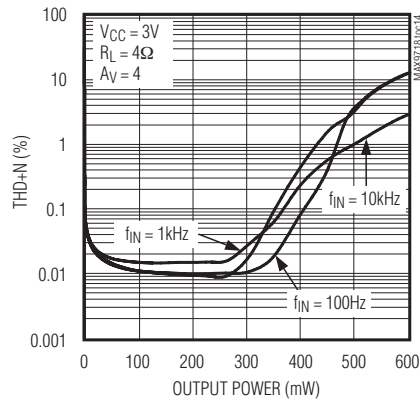
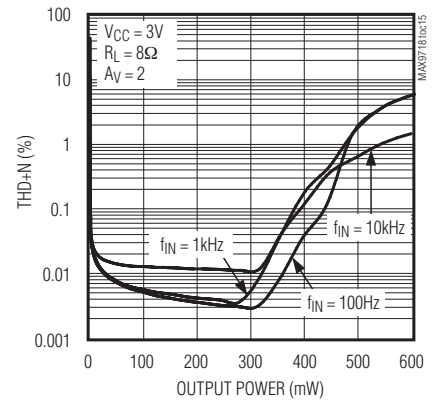
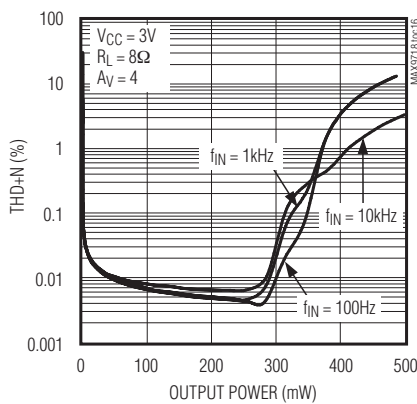
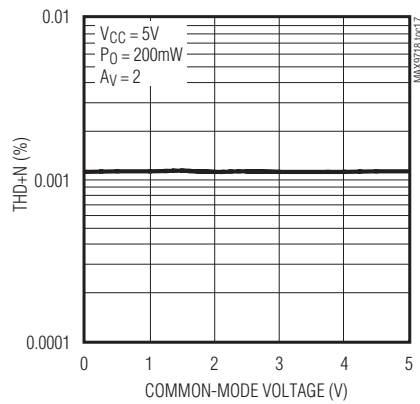
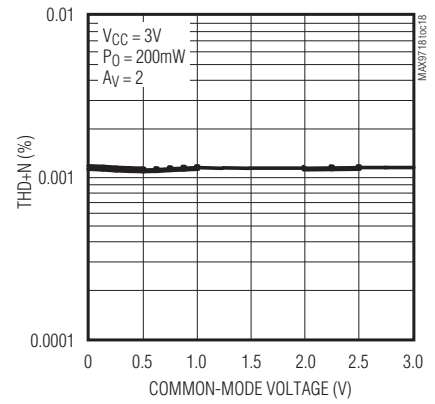
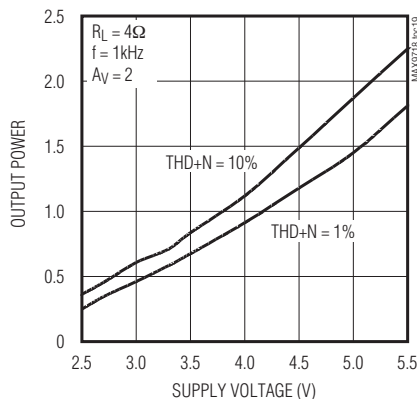
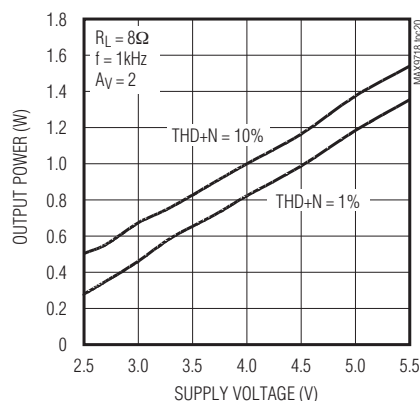
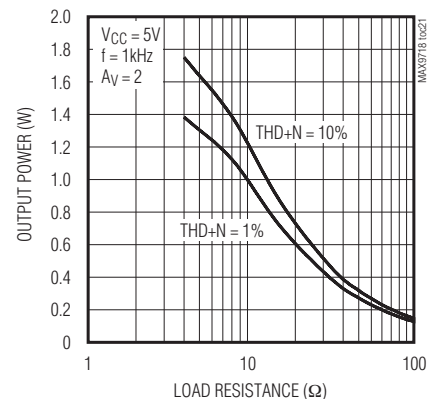


**TOTAL HARMONIC DISTORTION PLUS NOISE
vs. OUTPUT POWER**



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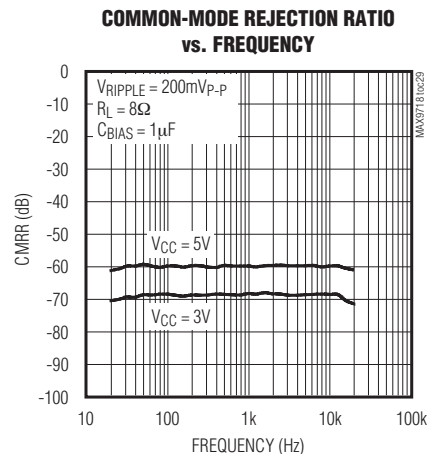
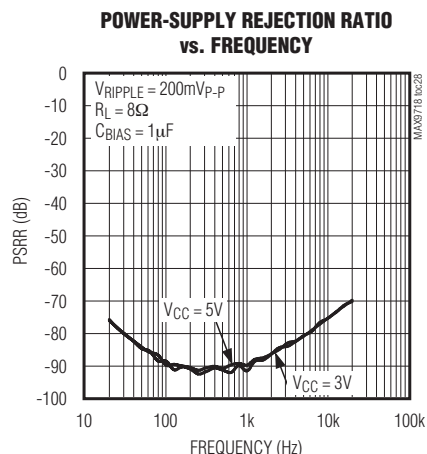
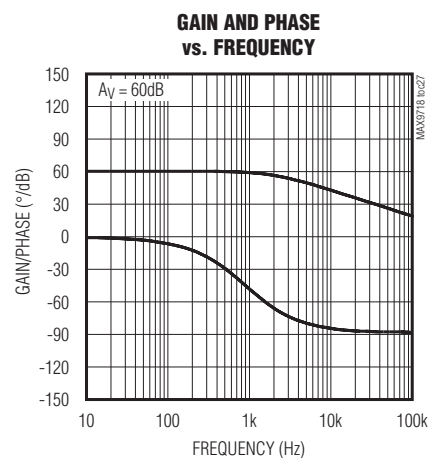
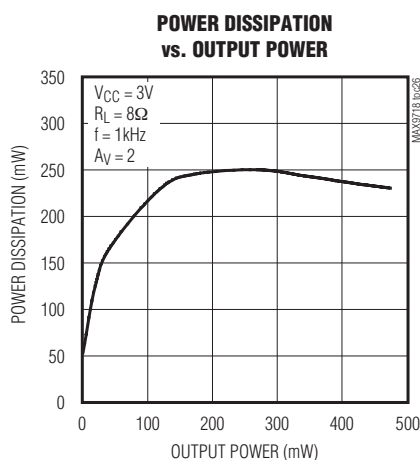
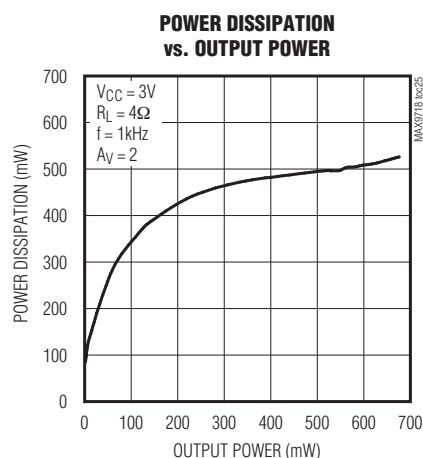
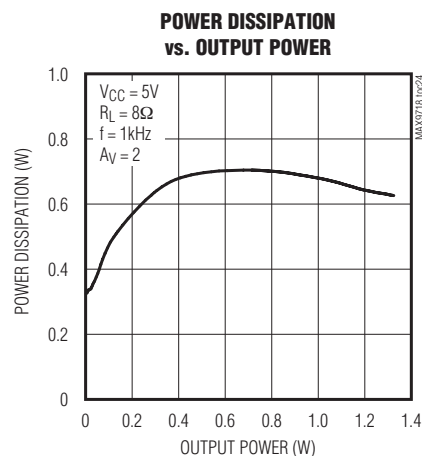
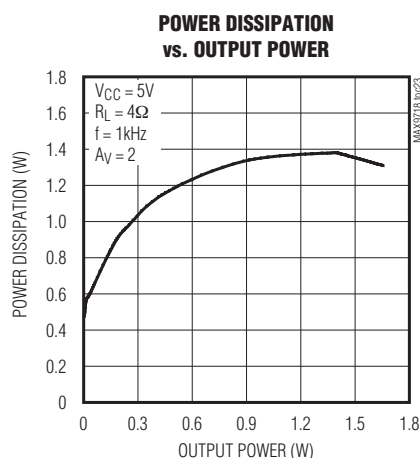
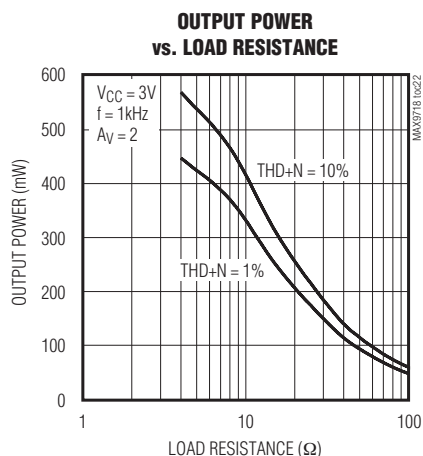
典型工作特性(续)

(V_{CC} = 5V, C_{BIAS} = 0.1μF, THD+N measurement bandwidth = 22Hz to 22kHz, T_A = +25°C, unless otherwise noted.)TOTAL HARMONIC DISTORTION PLUS NOISE
vs. OUTPUT POWERTOTAL HARMONIC DISTORTION PLUS NOISE
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vs. COMMON-MODE VOLTAGETOTAL HARMONIC DISTORTION PLUS NOISE
vs. COMMON-MODE VOLTAGEOUTPUT POWER
vs. SUPPLY VOLTAGEOUTPUT POWER
vs. SUPPLY VOLTAGEOUTPUT POWER
vs. LOAD RESISTANCE

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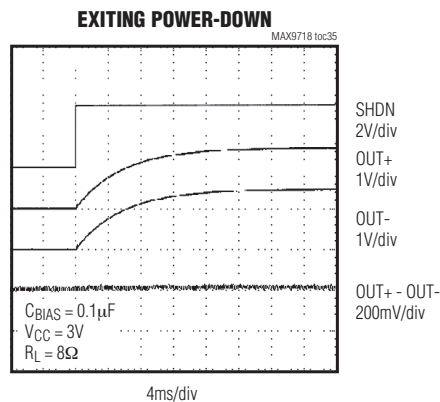
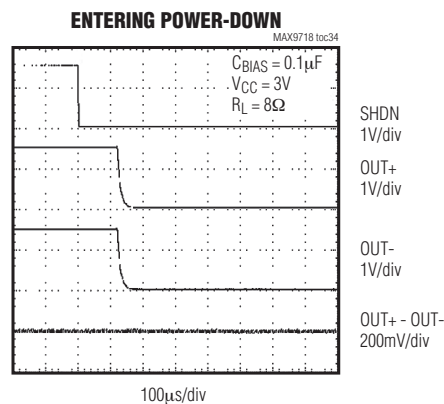
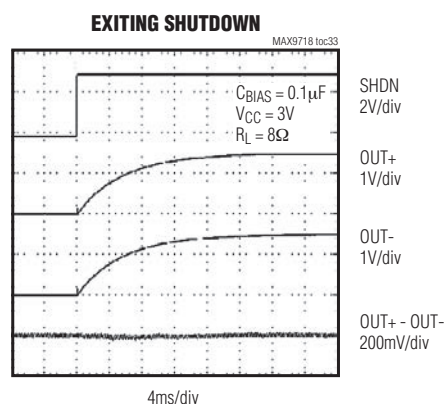
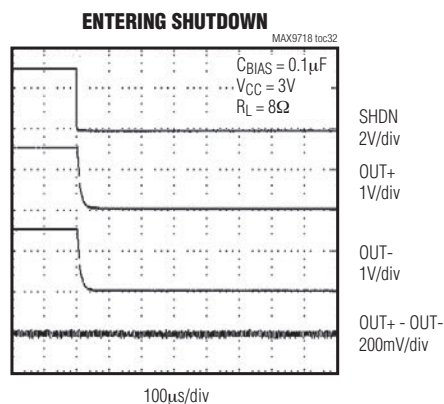
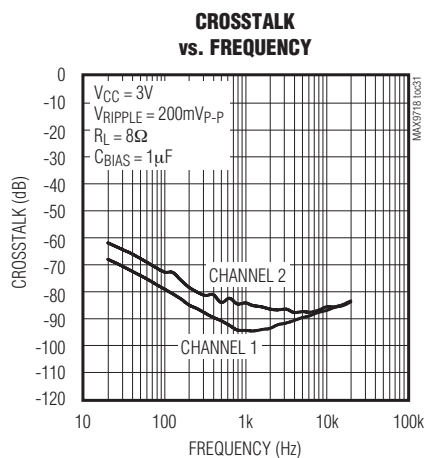
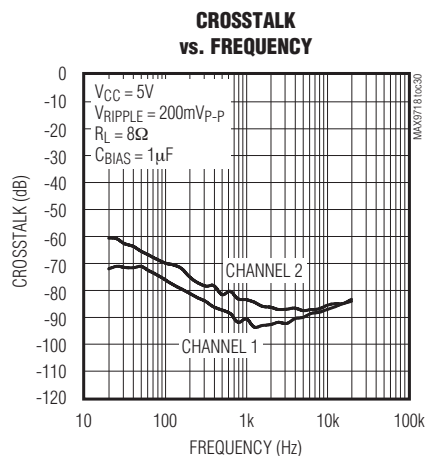
($V_{CC} = 5V$, $C_{BIAS} = 0.1\mu F$, THD+N measurement bandwidth = 22Hz to 22kHz, $T_A = +25^\circ C$, unless otherwise noted.)



低成本、单声道/立体声、 1.4W差分音频功率放大器

典型工作特性(续)

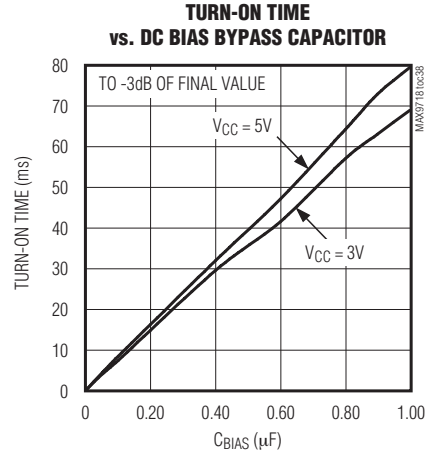
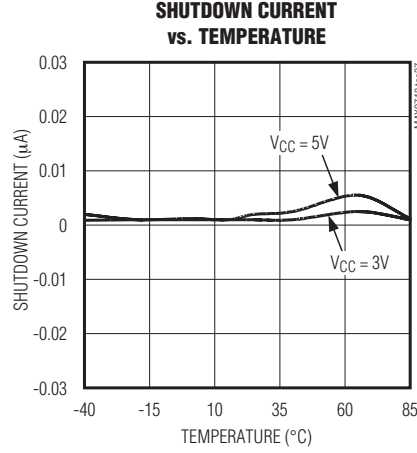
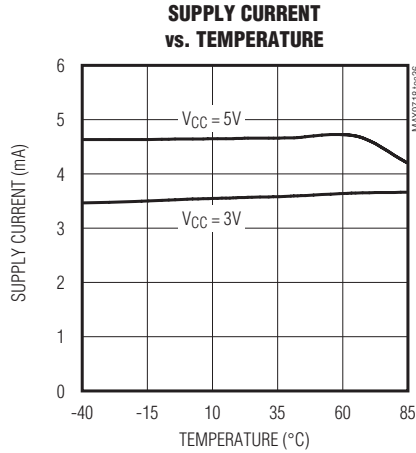
($V_{CC} = 5V$, $C_{BIAS} = 0.1\mu F$, THD+N measurement bandwidth = 22Hz to 22kHz, $T_A = +25^\circ C$, unless otherwise noted.)



低成本、单声道/立体声、 1.4W差分音频功率放大器

典型工作特性(续)

($V_{CC} = 5V$, $C_{BIAS} = 0.1\mu F$, THD+N measurement bandwidth = 22Hz to 22kHz, $T_A = +25^\circ C$, unless otherwise noted.)



引脚说明

引脚					名称	功能
MAX9718		MAX9719				
TDFN-EP/ μMAX	UCSP	TQFN-EP	UCSP	TSSOP-EP		
1	C2	—	—	—	SHDN	关断输入，SHDN的极性取决于SHDM的状态。
—	—	9	B3	11	$\overline{\text{SHDN}}$	关断输入，低电平有效的关断输入。
2	C1	—	—	—	IN-	反相输入。
3	B2	—	—	—	SHDM	关断模式极性输入，SHDM控制SHDN的极性。将SHDM接高电平，得到高电平有效的SHDN输入；将SHDM接低电平，得到低电平有效的SHDN输入(见表1)。
4	A1	—	—	—	IN+	同相输入。
5	A2	5	B2	7	BIAS	直流偏置旁路。
6	A3	—	—	—	OUT-	桥式放大器负输出。
7	B3	1, 6, 11	A2, C2, C4	3, 8, 13	GND	地。
8	—	13	—	15	N.C.	无连接，内部未连接。
9	B1	8, 14	A4, D3	16, 10	V _{CC}	电源。
10	C3	—	—	—	OUT+	桥式放大器正输出。
—	—	2	C1	4	INR+	右声道同相输入。
—	—	3	B1	5	INL-	左声道反相输入。
—	—	4	A1	6	INL+	左声道同相输入。
—	—	7	A3	9	OUTL+	左声道桥式放大器正输出。

低成本、单声道/立体声、 1.4W差分音频功率放大器

引脚说明(续)

引脚					名称	功能
TDFN-EP/ μMAX	UCSP	TQFN-EP	UCSP	TSSOP-EP		
—	—	10	B4	12	OUTL-	左声道桥式放大器负输出。
—	—	12	D4	14	OUTR+	右声道桥式放大器正输出。
—	—	15	D2	1	OUTR-	右声道桥式放大器负输出。
—	—	16	D1	2	INR-	右声道反相输入。
—	—	—	—	—	EP	裸焊盘，将EP与GND连接。

详细说明

MAX9718/MAX9719是1.4W BTL扬声器放大器。MAX9718是单声道扬声器放大器，而MAX9719是立体声扬声器放大器。两种器件都具有低功耗关断模式和业界领先的杂音抑制功能。MAX9718具有双输入关断方案，可以分别配置为高电平有效或低电平有效关断。这些器件由高输出电流音频放大器组成，音频放大器配置为BTL放大器(见功能框图)。提供可调增益和固定增益(0dB、3dB、6dB)产品。

BIAS

这些器件工作在2.7V至5.5V单电源，由内部产生共模偏置电压，该共模偏置电压相对于地电位为 $V_{CC}/2$ 。BIAS电路既提供杂音抑制，也为音频输出设置直流偏置电平。按照BIAS电容部分的说明选择旁路电容。不要在BIAS引脚接外部负载，以免影响整体性能。

关断模式

MAX9718/MAX9719具有100nA低功耗关断模式，可以降低静态电流损耗。进入关断模式后，器件的偏置电路被禁用，放大器输出变为高阻状态，BIAS端被驱动到GND。MAX9718的SHDM输入用来控制SHDN的极性。SHDM为高电平时，SHDN输入为高电平有效；SHDM为低电平时，SHDN输入为低电平有效(见表1)。MAX9719具有低电平有效的关断输入SHDN。

杂音抑制

MAX9718/MAX9719具有Maxim业界领先的杂音抑制电路。启动过程中，放大器共模偏置电压逐渐上升到直流偏置点。进入关断模式时，放大器输出之间具有100kΩ的高阻。这种结构大大降低了出现在音频波段的能量。

表1. 关断模式选择(MAX9718)

SHDM	SHDN	OPERATIONAL MODE
0	0	Shutdown
0	1	Normal operation
1	0	Normal operation
1	1	Shutdown

应用信息

BTL放大器

MAX9718/MAX9719使用差分方式驱动负载，这种配置称为桥接负载或BTL。BTL配置(图1)优于单端配置，单端配置的一个负载端接地。在相同条件下，差分方式驱动负载得到的输出电压是单端放大器的二倍。

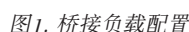
由于输出电压加倍，在下列公式中用 $2 \times V_{OUT(P-P)}$ 替代 $V_{OUT(P-P)}$ 可以得到四倍的输出功率：

$$V_{RMS} = \frac{V_{OUT(P-P)}}{2\sqrt{2}}$$

$$P_{OUT} = \frac{V_{RMS}^2}{R_L}$$

由于差分输出偏置在电源中点，负载两端没有净直流电压。这样就可以省去单端放大器中所需要的隔直电容。这些电容体积大、成本高，既浪费电路板空间，又降低了低频性能指标。

MAX9718/MAX9719



在标准工作条件下，MAX9718/MAX9719可以耗散绝大部分功率，在*Absolute Maximum Ratings*部分的Continuous Power Dissipation中给出了每种封装的最大功率耗散值，也可以用以下公式计算：

与单端配置相比，BTL配置输出功率的增加直接导致了内部功耗的增加。给定 V_{CC} 和负载后，内部功耗的最大值由下式计算：

为获得最佳的功率耗散与散热条件, μ MAX、TDFN、TOFN和TSSOP封装上的裸焊盘应与大面积地层相连。



R_F 可以是固定电阻或可变电阻，允许使用数控电位器在软件控制下改变增益。

低成本、单声道/立体声、 1.4W差分音频功率放大器

输入滤波器

全差分放大器的输入可以偏置在电源中点以外的电压。共模反馈电路用来调节输入偏置，确保输出偏置始终保持在电源中点处。只要共模输入电压在*Electrical Characteristics*表指定的额定工作范围以内，就不需要输入电容。

如果使用了输入电容，输入电容 C_{IN} 与 R_{IN} 一起构成了高通滤波器，可以消除输入信号中的直流偏置。交流耦合电容允许放大器为信号提供最佳的直流偏置。假定信号源阻抗为0，高通滤波器的-3dB点为：

$$f_{-3dB} = \frac{1}{2\pi R_{IN} C_{IN}}$$

如果 f_{-3dB} 设置过高，会影响放大器的低频响应。选用具有低电压系数电介质的电容，如钽或铝电解电容。陶瓷电容等高电压系数电容可能会导致低频失真加剧。

BIAS电容

BIAS引脚是内部产生的 $V_{CC}/2$ 偏置电压的输出端。BIAS旁路电容 C_{BIAS} 通过降低电源与共模偏置节点的噪声源可以改善PSRR和THD+N性能，并为扬声器放大器提供无杂音的启动直流偏置波形。用0.1 μ F电容将BIAS旁路到GND。大容值的 C_{BIAS} (高达1 μ F)可以改善PSRR性能，但使 t_{ON}/t_{OFF} 时间变慢。1 μ F C_{BIAS} 电容使导通/关闭时间放慢10倍，但使PSRR改善20dB (1kHz)。BIAS处不要接外部负载。

电源旁路

适当的电源旁路可以确保低噪声、低失真工作，在 V_{CC} 与GND之间接1 μ F陶瓷电容。根据具体应用的需求，可以添加额外的大电容。旁路电容应尽可能靠近器件安装。

布线与接地

良好的PCB布线是获得最佳性能的关键。在电源输入和放大器输出端使用宽的引线，以降低由于引线的寄生电阻所引起的损耗，并改善器件的散热。良好的接地可以改善音频性能、减小通道间串扰，并防止数字开关噪声耦合到音频信号中。

MAX9718/MAX9719的TDFN、TQFN、TSSOP和 μ MAX封装的下方都有散热裸焊盘。这个焊盘提供从管芯到PCB的直接导热通道，用来降低封装的热阻。如果需要的话，使用多个过孔将裸焊盘与地层相连。

UCSP应用信息

有关UCSP的最新应用细节，它的结构、外形尺寸、载带信息、PCB技术、焊球-焊盘布局、推荐的回流焊温度曲线以及可靠性测试结果等最新信息，请参考应用笔记1891：晶片级封装(WLP)及其应用。

选型指南

PART	MONO	STEREO	GAIN (dB)	SELECTABLE SHUTDOWN POLARITY
MAX9718A/H	✓	—	Adjustable	✓
MAX9718B/E	✓	—	0	✓
MAX9718C/F	✓	—	3	✓
MAX9718D/G	✓	—	6	✓
MAX9719A	—	✓	Adjustable	—
MAX9719B	—	✓	0	—
MAX9719C	—	✓	3	—
MAX9719D	—	✓	6	—

低成本、单声道/立体声、 1.4W差分音频功率放大器

订购信息(续)

PART	TEMP RANGE	PIN-PACKAGE	TOP MARK
MAX9718AEUB+	-40°C to +85°C	10 μ MAX-EP*	+AAAA
MAX9718BEBL+TG45	-40°C to +85°C	3 x 3 UCSP	+ADX
MAX9718BETB+T	-40°C to +85°C	10 TDFN-EP*	+AAW
MAX9718BEUB+	-40°C to +85°C	10 μ MAX-EP*	+AAAB
MAX9718CEBL+TG45	-40°C to +85°C	3 x 3 UCSP	+ADZ
MAX9718CETB+T	-40°C to +85°C	10 TDFN-EP*	+AAX
MAX9718CEUB+	-40°C to +85°C	10 μ MAX-EP*	+AAAC
MAX9718DEBL+TG45	-40°C to +85°C	3 x 3 UCSP	+AEA
MAX9718DETB+T	-40°C to +85°C	10 TDFN-EP*	+AAY
MAX9718DEUB+	-40°C to +85°C	10 μ MAX-EP*	+AAAD
MAX9718EEBL+TG45	-40°C to +85°C	3 x 3 UCSP	+AFB
MAX9718EETB+T	-40°C to +85°C	10 TDFN-EP*	+ASY
MAX9718EEUB+	-40°C to +85°C	10 μ MAX-EP*	+AAAJ
MAX9718FEBL+TG45	-40°C to +85°C	3 x 3 UCSP	+AFC
MAX9718FETB+T	-40°C to +85°C	10 TDFN-EP*	+ASZ
MAX9718FEUB+	-40°C to +85°C	10 μ MAX-EP*	+AAAK
MAX9718GEBL+TG45	-40°C to +85°C	3 x 3 UCSP	+AFD
MAX9718GETB+T	-40°C to +85°C	10 TDFN-EP*	+ATA

PART	TEMP RANGE	PIN-PACKAGE	TOP MARK
MAX9718GEUB+	-40°C to +85°C	10 μ MAX-EP*	+AAAL
MAX9718HEBL+TG45	-40°C to +85°C	3 x 3 UCSP	+AFE
MAX9718HETB+T	-40°C to +85°C	10 TDFN-EP*	+ATB
MAX9718HEUB+	-40°C to +85°C	10 μ MAX-EP*	+AAAM
MAX9719AEBE+T	-40°C to +85°C	4 x 4 UCSP	—
MAX9719AETE+	-40°C to +85°C	16 TQFN-EP*	—
MAX9719AEUE+	-40°C to +85°C	16 TSSOP-EP*	—
MAX9719BEBE+TG45	-40°C to +85°C	4 x 4 UCSP	—
MAX9719BETE+	-40°C to +85°C	16 TQFN-EP*	—
MAX9719BEUE+	-40°C to +85°C	16 TSSOP-EP*	—
MAX9719CEBE+TG45	-40°C to +85°C	4 x 4 UCSP	—
MAX9719CETE+	-40°C to +85°C	16 TQFN-EP*	—
MAX9719CEUE+	-40°C to +85°C	16 TSSOP-EP*	—
MAX9719DEBE+TG45	-40°C to +85°C	4 x 4 UCSP	—
MAX9719DETE+	-40°C to +85°C	16 TQFN-EP*	—
MAX9719DEUE+	-40°C to +85°C	16 TSSOP-EP*	—

+表示无铅(Pb)/符合RoHS标准的封装。

*EP = 裸焊盘。

G45表示管芯带有保护层。

UCSP标记信息



■: A1 Bump indicator

AAA: Product code

XXX: Lot code

芯片信息

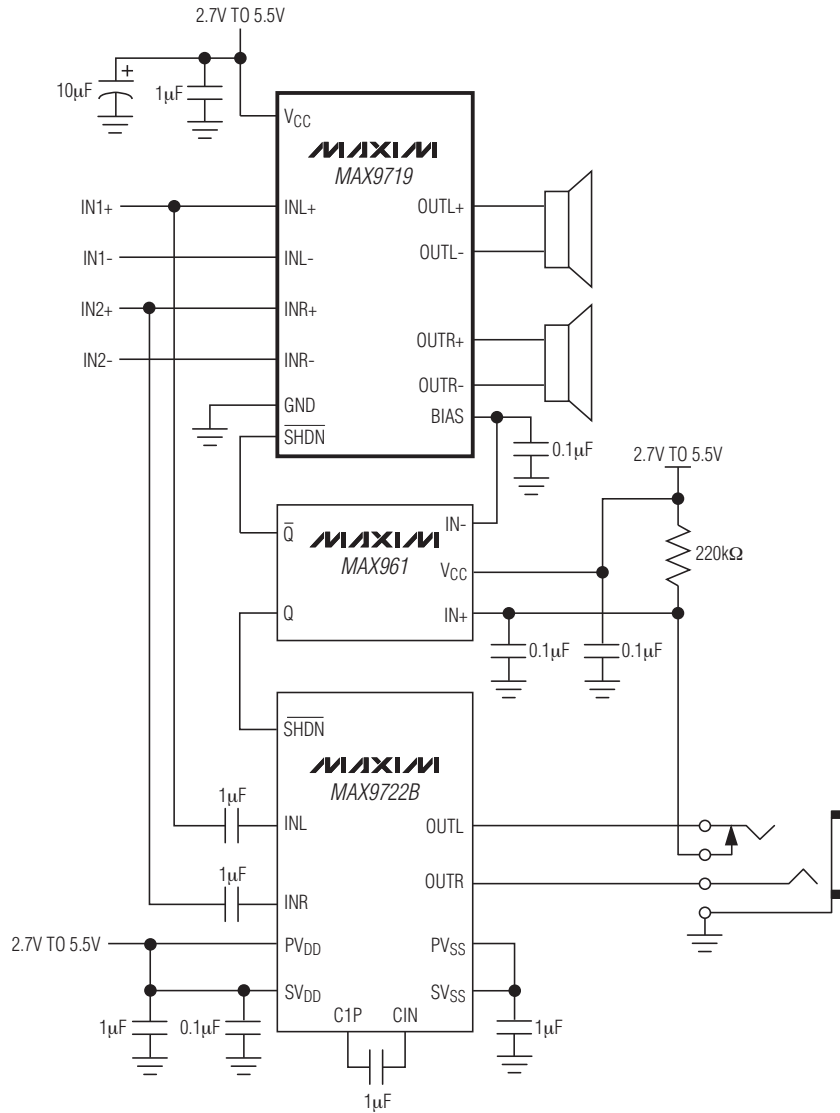
MAX9718 TRANSISTOR COUNT: 2359

MAX9719 TRANSISTOR COUNT: 4447

PROCESS: BiCMOS

低成本、单声道/立体声、 1.4W差分音频功率放大器

系统框图

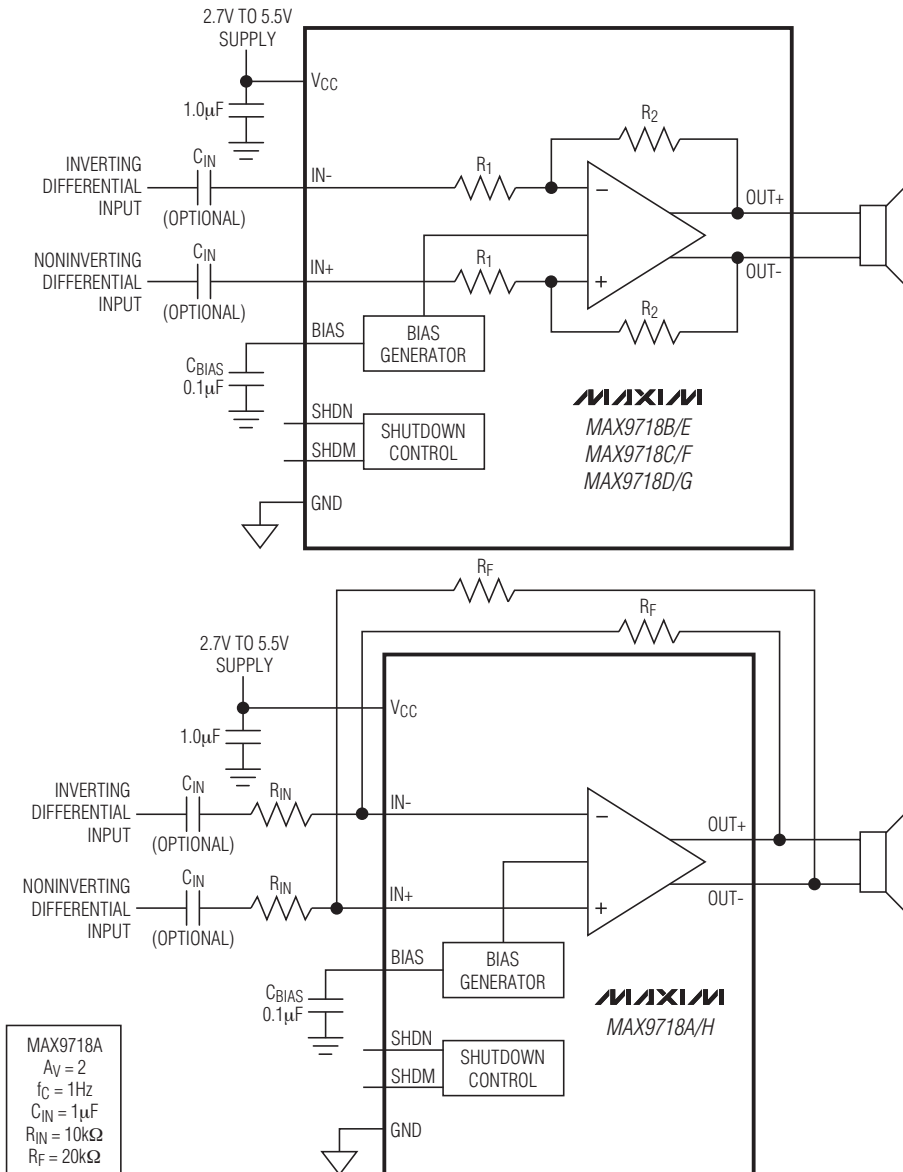


AUTOMATIC HEADPHONE DETECTION AND SPEAKER DISABLE CIRCUIT

低成本、单声道/立体声、 1.4W差分音频功率放大器

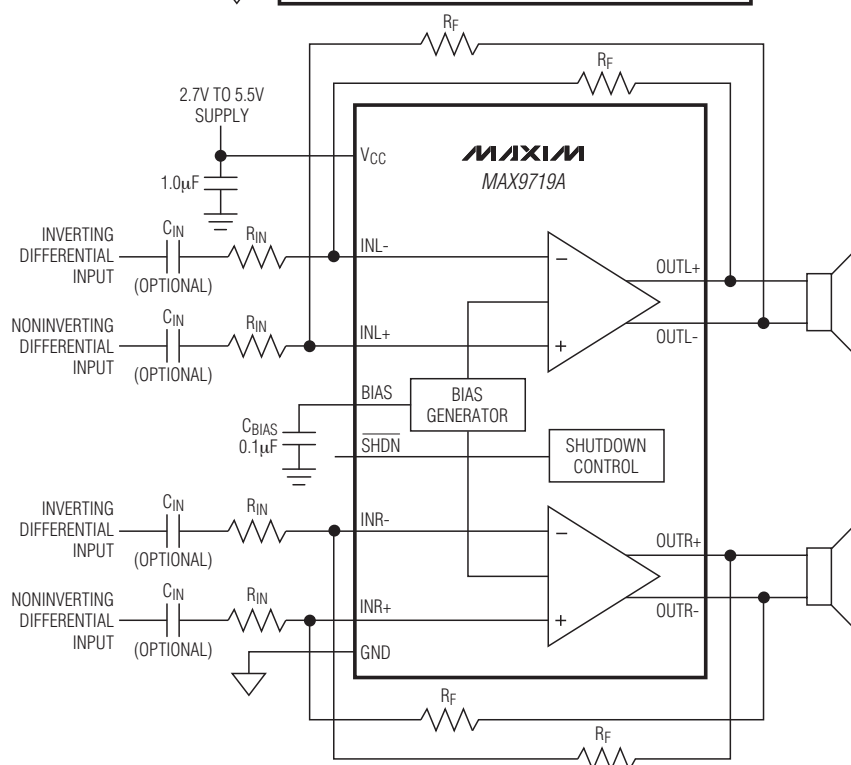
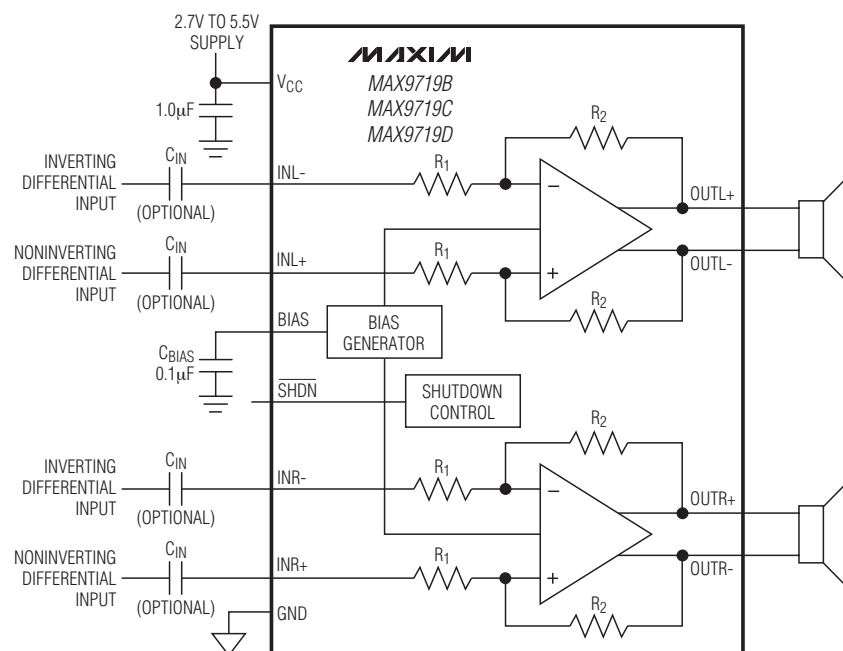
功能框图

MAX9718/MAX9719



低成本、单声道/立体声、 1.4W差分音频功率放大器

功能框图(续)



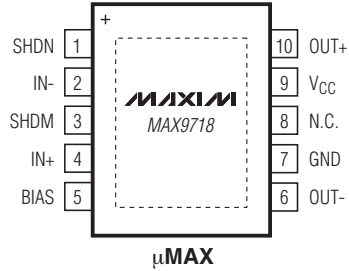
MAX9719A
 $A_V = 2$
 $f_C = 1\text{Hz}$
 $C_{IN} = 1\mu\text{F}$
 $R_{IN} = 10\text{k}\Omega$
 $R_F = 20\text{k}\Omega$

低成本、单声道/立体声、 1.4W差分音频功率放大器

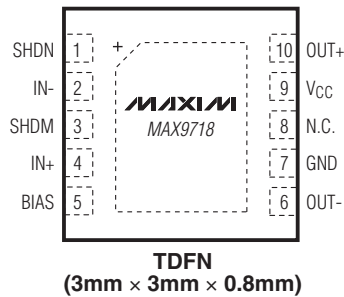
引脚配置

MAX9718/MAX9719

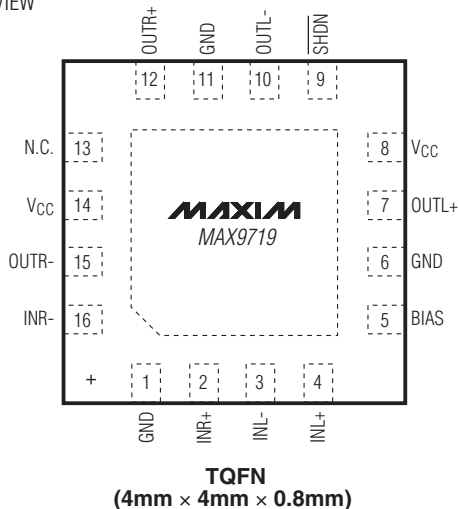
TOP VIEW



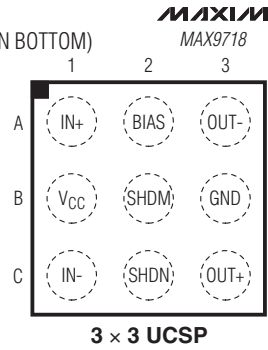
TOP VIEW



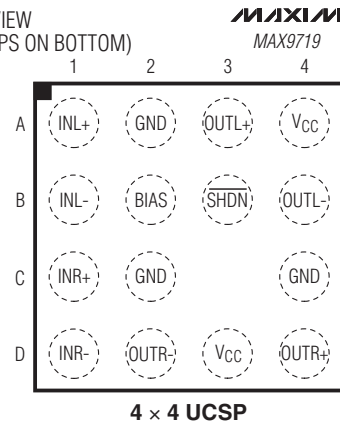
TOP VIEW



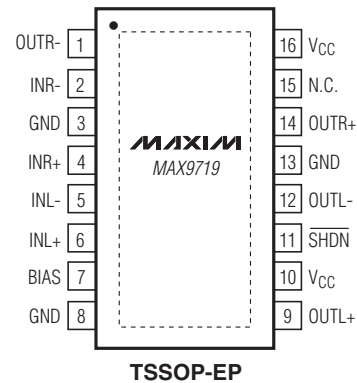
TOP VIEW
(BUMPS ON BOTTOM)



TOP VIEW
(BUMPS ON BOTTOM)



TOP VIEW

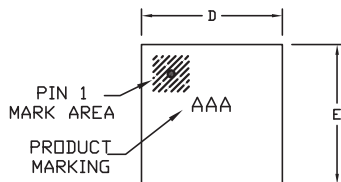


低成本、单声道/立体声、 1.4W差分音频功率放大器

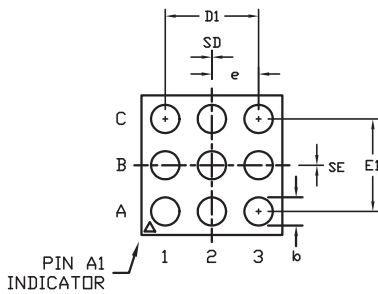
封装信息

如需最近的封装外形信息和焊盘布局, 请查询 china.maxim-ic.com/packages. 请注意, 封装编码中的“+”、“#”或“-”仅表示RoHS状态。封装图中可能包含不同的后缀字符, 但封装图只与封装有关, 与RoHS状态无关。

封装类型	封装编码	文档编号
3 x 3 UCSP	B9+1	21-0093
10 TDFN-EP	T1033+1	21-0137
10 μ MAX	U10E+3	21-0109
4 x 4 UCSP	B16+6	21-0101
16 TQFN-EP	T1644+4	21-0139
16 TSSOP-EP	U16E+3	21-0108



TOP VIEW



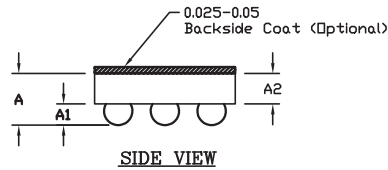
BOTTOM VIEW

COMMON DIMENSIONS	
A	0.62±0.05-0.08
A1	0.29±0.02
A2	0.33 REF.
b	0.35±0.03
D1	1.00 BASIC
E1	1.00 BASIC
e	0.50 BASIC
SD	0.00 BASIC
SE	0.00 BASIC

PKG. CODE	VARIABLE DIMENSIONS		DEPOPULATED SOLDER BALLS
	D	E	
B9-1	1.52±0.05	1.52±0.05	NONE
B9-2	1.52±0.05	1.52±0.05	B2
B9-3	1.52±0.05	1.52±0.05	B1, B2, B3
B9-4	1.60±0.05	1.60±0.05	NONE
B9-5	1.60±0.05	1.60±0.05	B2
B9-6	1.60±0.05	1.60±0.05	B1, B2, B3
B9-7	1.52±0.05	1.52±0.05	A2, B1, B2, B3, C2
B9-8	1.98±0.05	1.75±0.05	B1, B2, B3

NOTES:

1. All dimensions in millimeters.
2. Outer dimension (D & E) is defined by center lines between scribe lines.
3. Marking shown is for package orientation reference only. Number of characters and lines vary per product.
4. All dimensions are applicable to Leaded (-), PbFree (+), and MaxFilm parts/pkg codes.



MAXIM		
TITLE: PACKAGE OUTLINE, 9 BUMPS, 3X3 ARRAY, UCSP (B) PKG.		
APPROVAL	DOCUMENT CONTROL NO. 21-0093	REV. M 1/1

—DRAWING NOT TO SCALE—

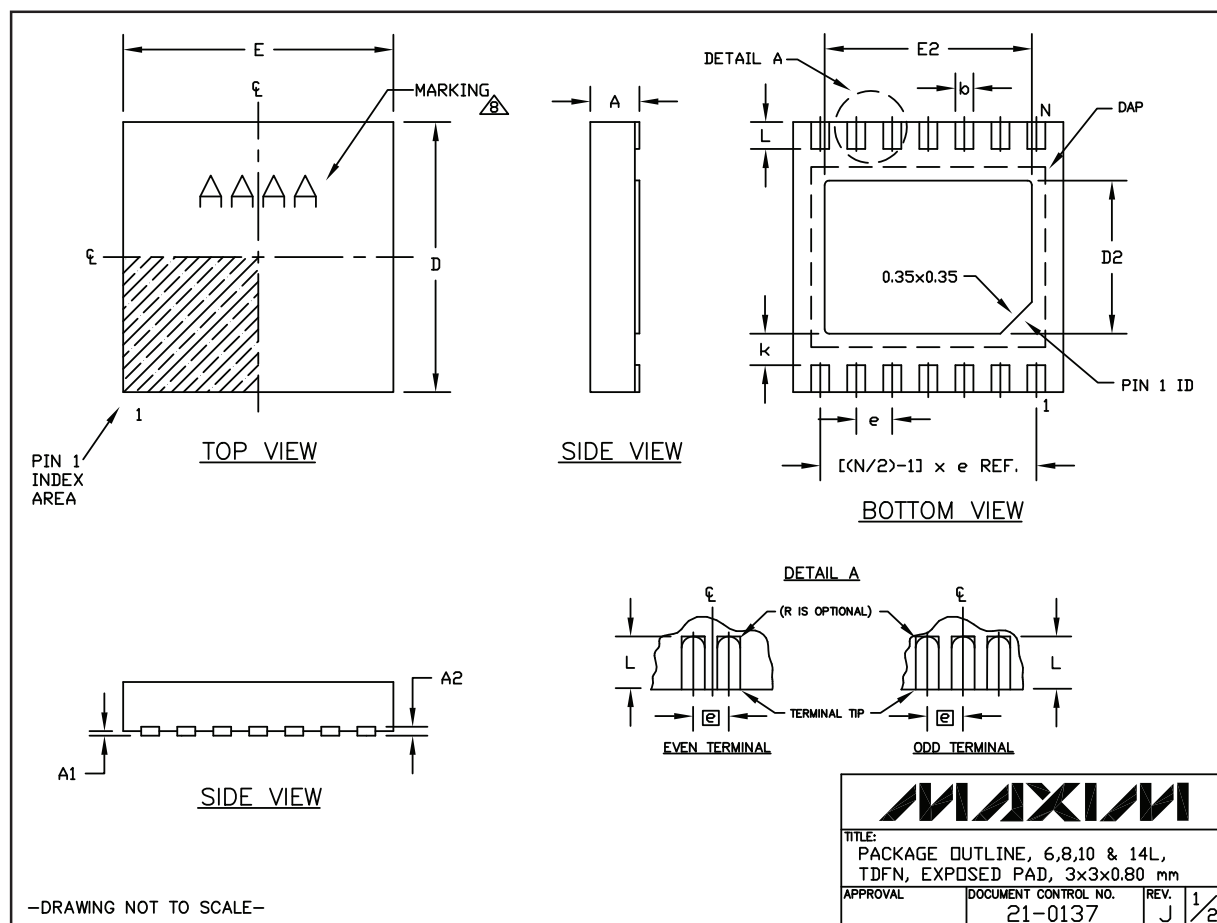
9LUCSP, 3x3.EPS

低成本、单声道/立体声、 1.4W差分音频功率放大器

封装信息(续)

如需最近的封装外形信息和焊盘布局, 请查询 china.maxim-ic.com/packages. 请注意, 封装编码中的“+”、“#”或“-”仅表示RoHS状态。封装图中可能包含不同的尾缀字符, 但封装图只与封装有关, 与RoHS状态无关。

MAX9718/MAX9719



低成本、单声道/立体声、 1.4W差分音频功率放大器

封装信息(续)

如需最近的封装外形信息和焊盘布局, 请查询 china.maxim-ic.com/packages. 请注意, 封装编码中的“+”、“#”或“-”仅表示RoHS状态。封装图中可能包含不同的尾缀字符, 但封装图只与封装有关, 与RoHS状态无关。

COMMON DIMENSIONS		
SYMBOL	MIN.	MAX.
A	0.70	0.80
D	2.90	3.10
E	2.90	3.10
A1	0.00	0.05
L	0.20	0.40
k	0.25 MIN.	
A2	0.20 REF.	

PACKAGE VARIATIONS								
PKG. CODE	N	D2	E2	e	JEDEC SPEC	b	[(N/2)-1] x e	
T633-2	6	1.50±0.10	2.30±0.10	0.95 BSC	MO229 / WEEA	0.40±0.05	1.90 REF	
T833-2	8	1.50±0.10	2.30±0.10	0.65 BSC	MO229 / WEEC	0.30±0.05	1.95 REF	
T833-3	8	1.50±0.10	2.30±0.10	0.65 BSC	MO229 / WEEC	0.30±0.05	1.95 REF	
T1033-1	10	1.50±0.10	2.30±0.10	0.50 BSC	MO229 / WEED-3	0.25±0.05	2.00 REF	
T1033MK-1	10	1.50±0.10	2.30±0.10	0.50 BSC	MO229 / WEED-3	0.25±0.05	2.00 REF	
T1033-2	10	1.50±0.10	2.30±0.10	0.50 BSC	MO229 / WEED-3	0.25±0.05	2.00 REF	
T1433-1	14	1.70±0.10	2.30±0.10	0.40 BSC	----	0.20±0.05	2.40 REF	
T1433-2	14	1.70±0.10	2.30±0.10	0.40 BSC	----	0.20±0.05	2.40 REF	
T1433-3F	14	1.70±0.10	2.30±0.10	0.40 BSC	----	0.20±0.05	2.40 REF	

NOTES:

1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
2. COPLANARITY SHALL NOT EXCEED 0.08 mm.
3. WARPAGE SHALL NOT EXCEED 0.10 mm.
4. PACKAGE LENGTH/PACKAGE WIDTH ARE CONSIDERED AS SPECIAL CHARACTERISTIC(S).
5. DRAWING CONFORMS TO JEDEC MO229, EXCEPT DIMENSIONS "D2" AND "E2", AND T1433-1 & T1433-2.
6. "N" IS THE TOTAL NUMBER OF LEADS.
7. NUMBER OF LEADS SHOWN ARE FOR REFERENCE ONLY.
8. MARKING IS FOR PACKAGE ORIENTATION REFERENCE ONLY.
9. ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND PbFREE (+) PKG. CODES.

-DRAWING NOT TO SCALE-

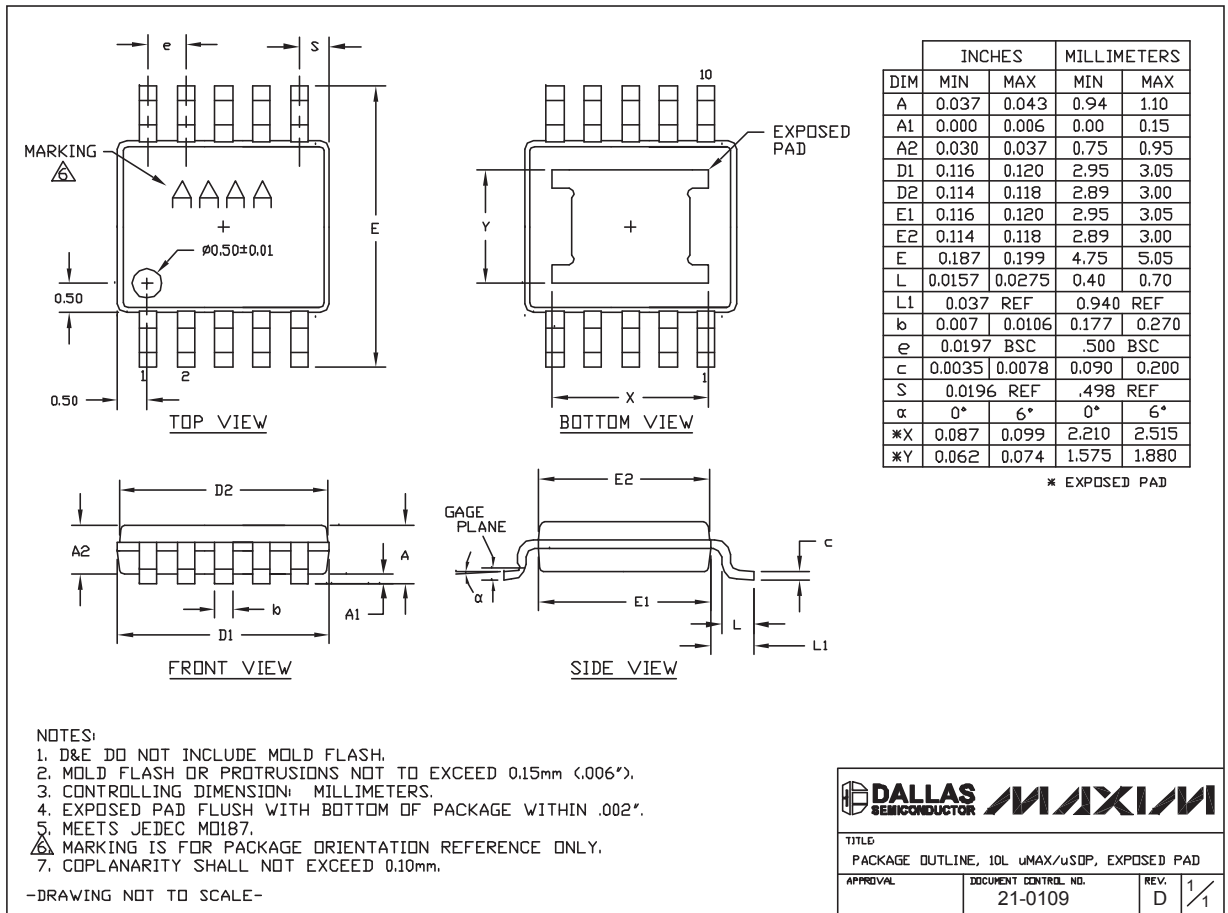
		
TITLE: PACKAGE OUTLINE, 6,8,10 & 14L, TDFN, EXPOSED PAD, 3x3x0.80 mm		
APPROVAL	DOCUMENT CONTROL NO. 21-0137	REV. J 2/2

低成本、单声道/立体声、 1.4W差分音频功率放大器

封装信息(续)

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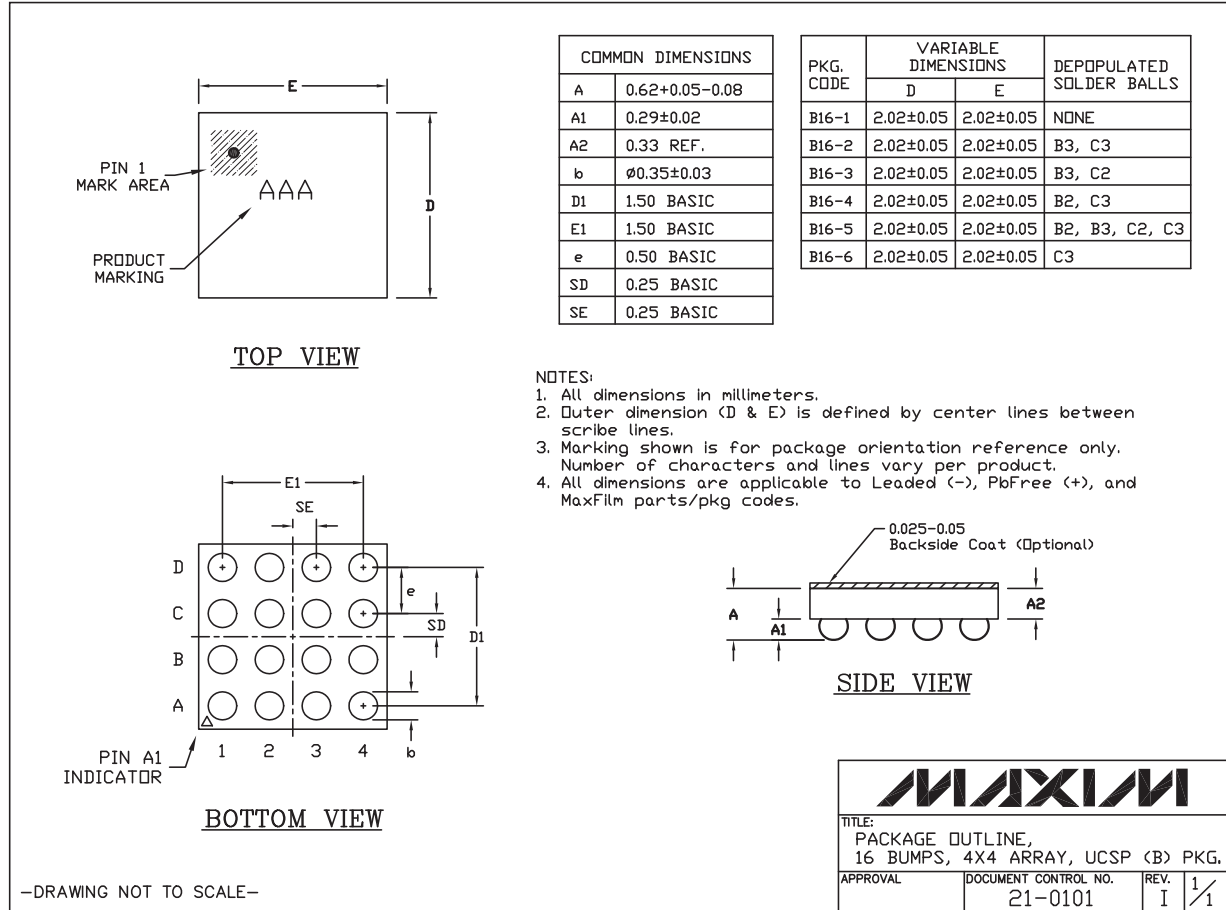
MAX9718/MAX9719



低成本、单声道/立体声、 1.4W差分音频功率放大器

封装信息(续)

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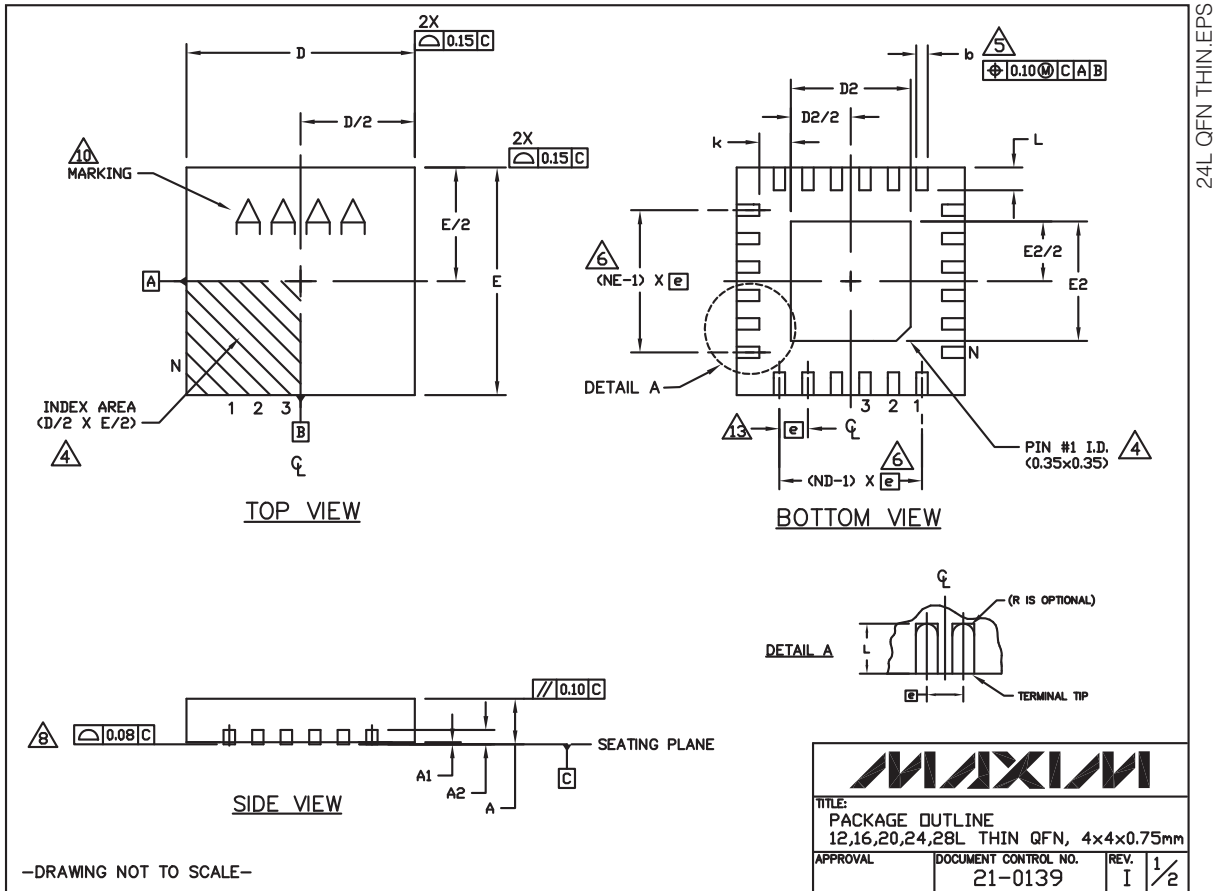


16LUCSP.EPS

低成本、单声道/立体声、 1.4W差分音频功率放大器

封装信息(续)

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MAX9718/MAX9719

低成本、单声道/立体声、 1.4W差分音频功率放大器

封装信息(续)

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COMMON DIMENSIONS															
PKG	12L 4x4			16L 4x4			20L 4x4			24L 4x4			28L 4x4		
REF.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80
A1	0.0	0.02	0.05	0.0	0.02	0.05	0.0	0.02	0.05	0.0	0.02	0.05	0.0	0.02	0.05
A2	0.20 REF			0.20 REF			0.20 REF			0.20 REF			0.20 REF		
b	0.25	0.30	0.35	0.25	0.30	0.35	0.20	0.25	0.30	0.18	0.23	0.30	0.15	0.20	0.25
D	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10
E	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10
e	0.80 BSC.			0.65 BSC.			0.50 BSC.			0.50 BSC.			0.40 BSC.		
k	0.25	-	-	0.25	-	-	0.25	-	-	0.25	-	-	0.25	-	-
L	0.45	0.55	0.65	0.45	0.55	0.65	0.45	0.55	0.65	0.30	0.40	0.50	0.30	0.40	0.50
N	12			16			20			24			28		
ND	3			4			5			6			7		
NE	3			4			5			6			7		
JeDEC Vpr.	WGGB			WGGC			WGDD-1			WGDD-2			WGGE		

EXPOSED PAD VARIATIONS						
PKG. CODES	D2			E2		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
T1244-3	1.95	2.10	2.25	1.95	2.10	2.25
T1244-4	1.95	2.10	2.25	1.95	2.10	2.25
T1644-3	1.95	2.10	2.25	1.95	2.10	2.25
T1644-4	1.95	2.10	2.25	1.95	2.10	2.25
T2044-2	1.95	2.10	2.25	1.95	2.10	2.25
T2044-3	1.95	2.10	2.25	1.95	2.10	2.25
T2444-2	1.95	2.10	2.25	1.95	2.10	2.25
T2444-3	2.45	2.60	2.63	2.45	2.60	2.63
T2444-4	2.45	2.60	2.63	2.45	2.60	2.63
T2444N-4	2.45	2.60	2.63	2.45	2.60	2.63
T2444M-1	2.45	2.60	2.63	2.45	2.60	2.63
T2844-1	2.50	2.60	2.70	2.50	2.60	2.70

NOTES:

- DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M-1994.
- ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.
- N IS THE TOTAL NUMBER OF TERMINALS.
- THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION SHALL CONFORM TO JEDEC 95-1 SPP-012. DETAILS OF TERMINAL #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE TERMINAL #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE.
- DIMENSION b APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.25mm AND 0.30mm FROM TERMINAL TIP.
- ND AND NE REFER TO THE NUMBER OF TERMINALS ON EACH D AND E SIDE RESPECTIVELY.
- DEPOPULATION IS POSSIBLE IN A SYMMETRICAL FASHION.
- COPLANARITY APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE TERMINALS.
- DRAWING CONFORMS TO JEDEC MO220, EXCEPT FOR T2444-3, T2444-4 AND T2844-1.
- MARKING IS FOR PACKAGE ORIENTATION REFERENCE ONLY.
- COPLANARITY SHALL NOT EXCEED 0.08mm.
- WARPAGE SHALL NOT EXCEED 0.10mm.
- LEAD CENTERLINES TO BE AT TRUE POSITION AS DEFINED BY BASIC DIMENSION 'e', ± 0.05 .
- NUMBER OF LEADS SHOWN ARE FOR REFERENCE ONLY.
- ALL DIMENSIONS ARE THE SAME FOR LEADED (-) & PbFREE (+) PACKAGE CODES.

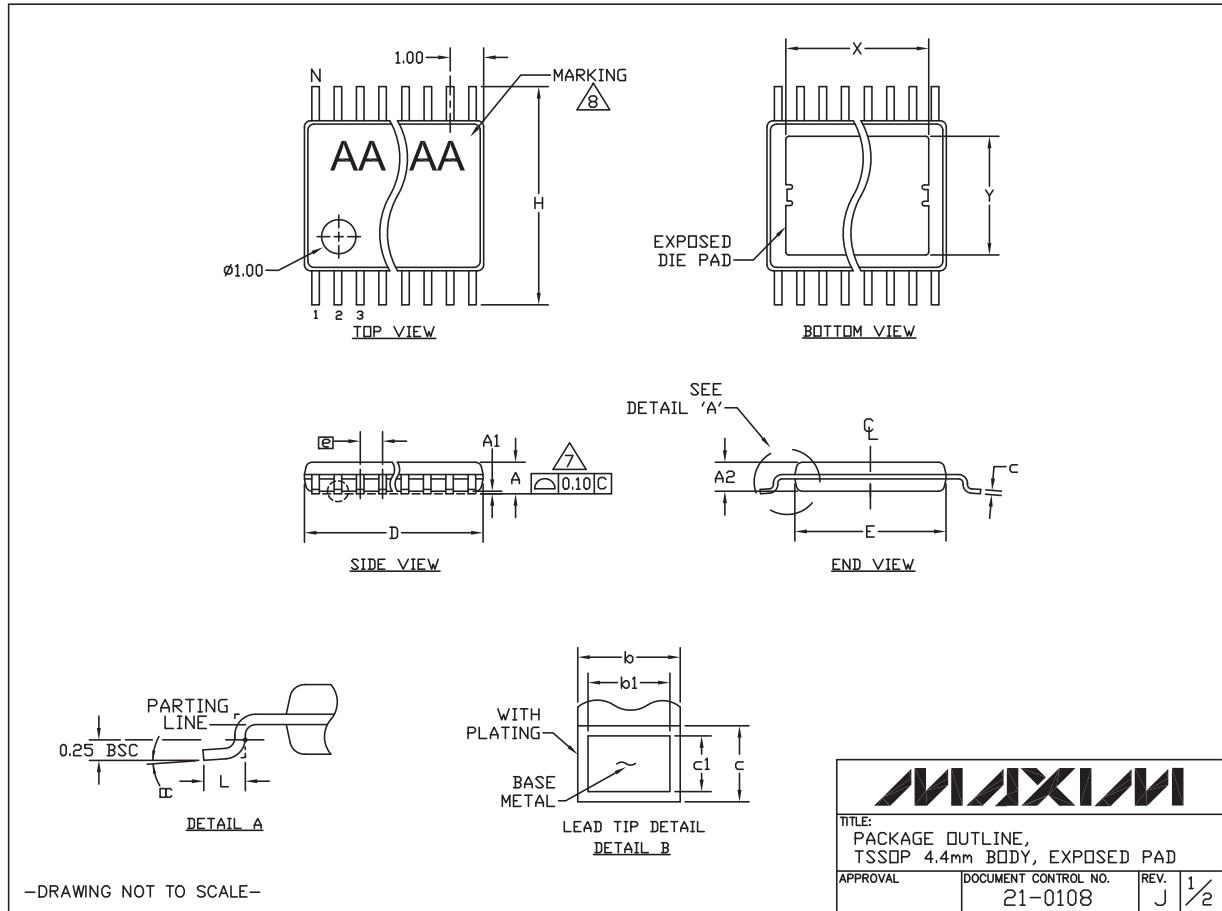
-DRAWING NOT TO SCALE-

MAXIM			
TITLE: PACKAGE OUTLINE 12,16,20,24,28L THIN QFN, 4x4x0.75mm			
APPROVAL	DOCUMENT CONTROL NO. 21-0139	REV. I	2/2

低成本、单声道/立体声、 1.4W差分音频功率放大器

封装信息(续)

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修订历史

修订号	修订日期	说明	修改页
5	2/08	更新了引脚配置。	17
6	3/09	在订购信息中增加了无铅及G45封装选项。	1, 13
7	4/10	更新了9焊球和16焊球UCSP封装的连续功耗指标，更正了引脚说明部分中的错误。	2, 9

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电话：010-6211 5199
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